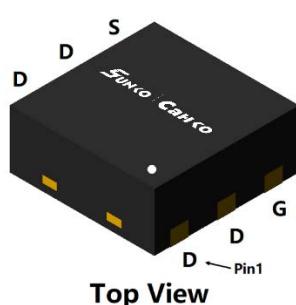
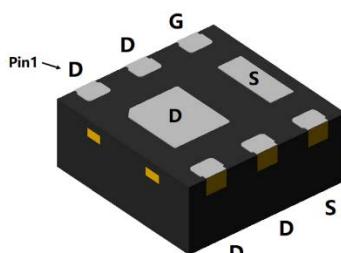


P-Channel Enhancement Mode Field Effect Transistor

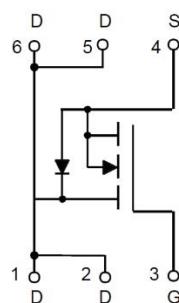


Top View



Bottom View

DFN2020-6L



Product Summary

- V_{DS} -20V
- I_D -16A
- $R_{DS(ON)}$ (at $V_{GS} = -4.5V$) <19mohm
- $R_{DS(ON)}$ (at $V_{GS} = -2.5V$) <22mohm
- $R_{DS(ON)}$ (at $V_{GS} = -1.8V$) <30mohm

General Description

- Trench Power MV MOSFET technology
- High density cell design for Low $R_{DS(ON)}$
- High Speed switching
- Epoxy Meets UL 94 V-0 Flammability Rating
- Halogen Free

Applications

- Battery protection
- Load switch
- Power management

Absolute Maximum Ratings ($T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter		Symbol	Maximum	Unit
Drain-source Voltage		V_{DS}	-20	V
Gate-source Voltage		V_{GS}	± 10	V
Drain Current	$T_c=25^\circ\text{C}$ @ Steady State	I_D	-16	A
	$T_c=70^\circ\text{C}$ @ Steady State		-12.8	
Pulsed Drain Current ^A		I_{DM}	-64	A
Total Power Dissipation @ $T_c=25^\circ\text{C}$		P_D	18	W
Total Power Dissipation @ $T_A=25^\circ\text{C}$		P_D	1.66	W
Thermal Resistance Junction-to-Case @ Steady State		$R_{\theta JC}$	6.9	$^\circ\text{C} / \text{W}$
Thermal Resistance Junction-to-Ambient @ Steady State ^B		$R_{\theta JA}$	75	$^\circ\text{C} / \text{W}$
Junction and Storage Temperature Range		T_J, T_{STG}	-55~+150	$^\circ\text{C}$

Ordering Information (Example)

PREFERRED P/N	PACKING CODE	Marking	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
SCQ1216A	F1	Q1216	3000	30000	120000	7" reel

■ Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Static Parameter						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=-250\mu\text{A}$	-20			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}}=-20\text{V}, V_{\text{GS}}=0\text{V}, T_c=25^\circ\text{C}$			-1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{\text{GS}}= \pm 10\text{V}, V_{\text{DS}}=0\text{V}$			± 100	nA
Gate Threshold Voltage	$V_{\text{GS(th)}}$	$V_{\text{DS}}= V_{\text{GS}}, I_{\text{D}}=-250\mu\text{A}$	-0.4	-0.62	-1.0	V
Static Drain-Source On-Resistance	$R_{\text{DS(ON)}}$	$V_{\text{GS}}= -4.5\text{V}, I_{\text{D}}=-10\text{A}$		11	19	$\text{m}\Omega$
		$V_{\text{GS}}= -2.5\text{V}, I_{\text{D}}=-6.5\text{A}$		14	22	
		$V_{\text{GS}}= -1.8\text{V}, I_{\text{D}}=-4.0\text{A}$		20	30	
Diode Forward Voltage	V_{SD}	$I_{\text{S}}=-13\text{A}, V_{\text{GS}}=0\text{V}$		-0.8	-1.2	V
Maximum Body-Diode Continuous Current	I_{S}				-13	A
Dynamic Parameters						
Input Capacitance	C_{iss}	$V_{\text{DS}}=-10\text{V}, V_{\text{GS}}=0\text{V}, f=1\text{MHz}$		2992		pF
Output Capacitance	C_{oss}			330		
Reverse Transfer Capacitance	C_{rss}			272		
Switching Parameters						
Total Gate Charge	Q_g	$V_{\text{GS}}=-10\text{V}, V_{\text{DS}}=-15\text{V}, I_{\text{D}}=-9.1\text{A}$		72.8		nC
Gate Source Charge	Q_{gs}			6.6		
Gate Drain Charge	Q_{gd}			10.1		
Reverse Recovery Charge	Q_{rr}	$I_{\text{F}}=-6\text{A}, di/dt=100\text{A/us}$		34		ns
Reverse Recovery Time	t_{rr}			67		
Turn-on Delay Time	$t_{\text{D(on)}}$			7		
Turn-on Rise Time	t_r	$V_{\text{GS}}=-10\text{V}, V_{\text{DS}}=-15\text{V}, I_{\text{D}}=-6\text{A}, R_{\text{GEN}}=2.5\Omega$		33		ns
Turn-off Delay Time	$t_{\text{D(off)}}$			130		
Turn-off Fall Time	t_f			132		

A. Pulse Test: Pulse Width $\leq 300\text{us}$, Duty cycle $\leq 2\%$.B. $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistance, where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{\theta JC}$ is guaranteed by design, while $R_{\theta JA}$ is determined by the board design. The maximum rating presented here is based on mounting on a 1 in 2 pad of 2oz copper.

■ Typical Performance Characteristics

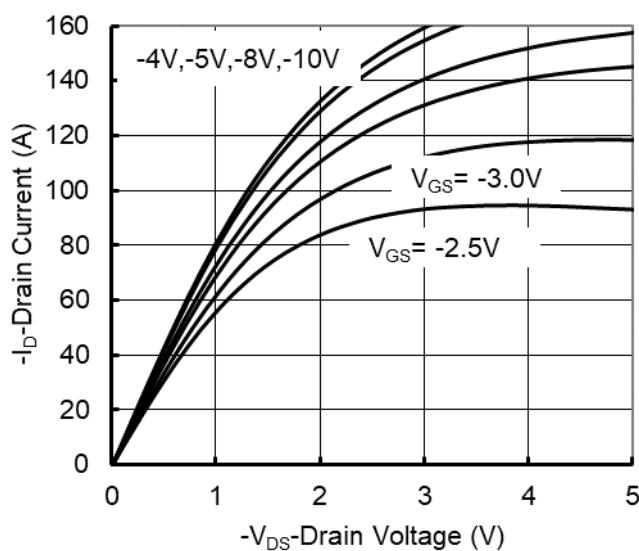


Figure 1. Output Characteristics

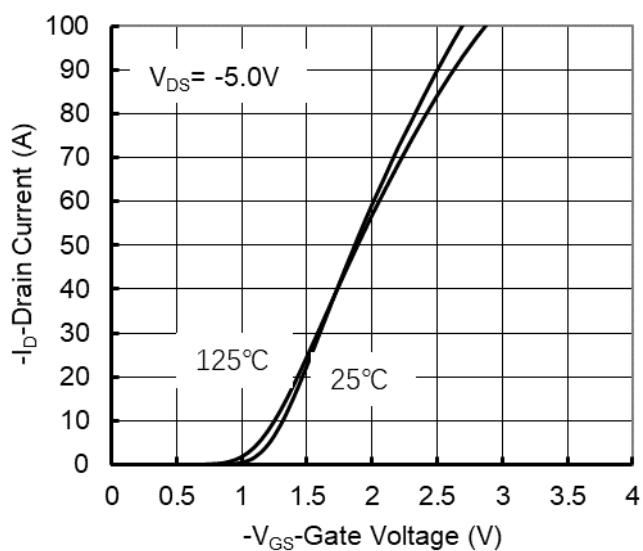


Figure 2. Transfer Characteristics

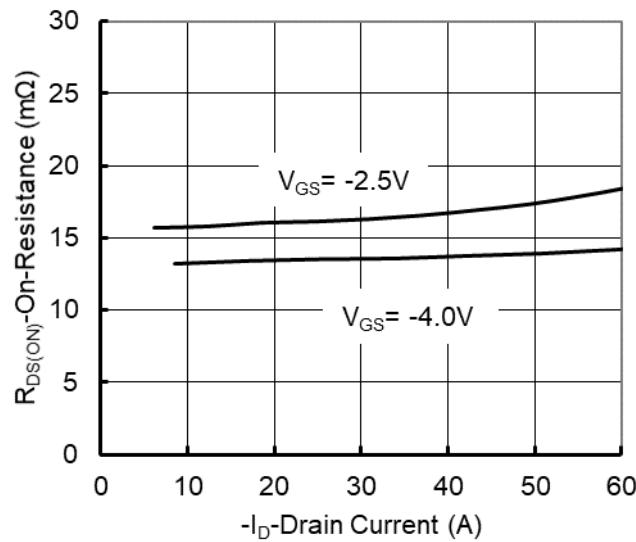


Figure 3. On-Resistance vs. Drain Current and Gate Voltage

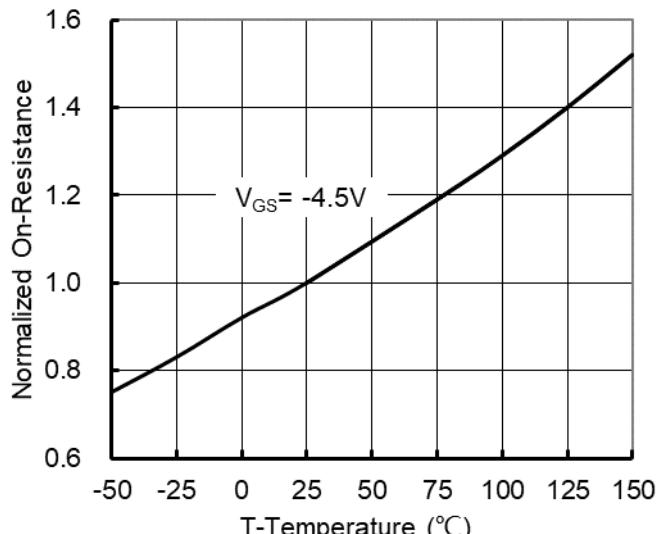


Figure 4. On-Resistance vs. Junction Temperature

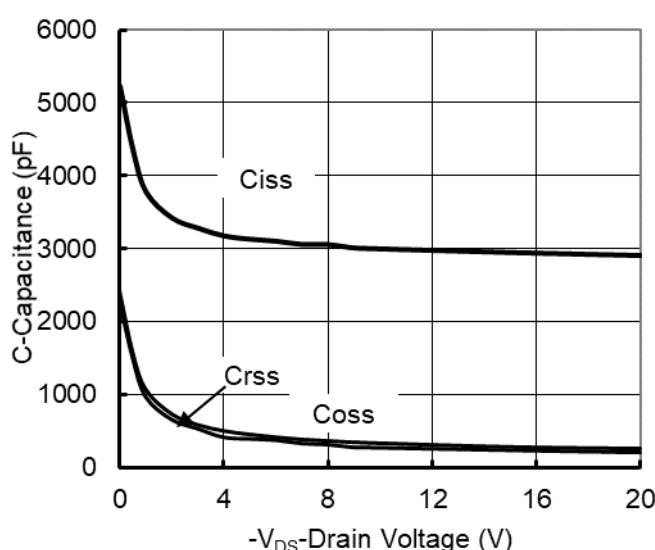


Figure 5. Capacitance Characteristics

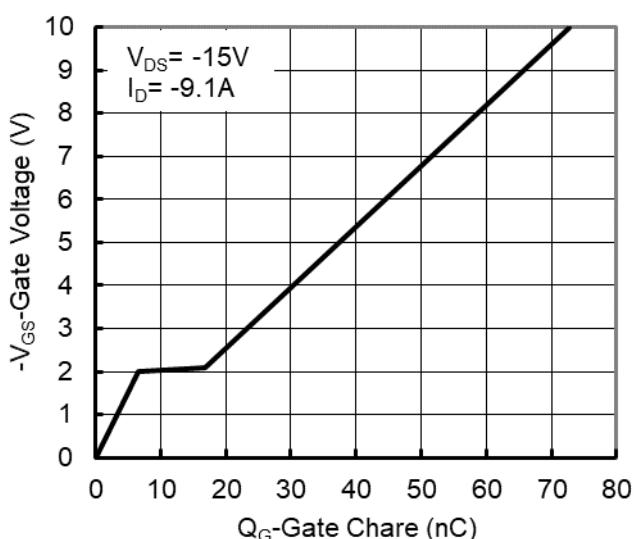


Figure 6. Gate Charge

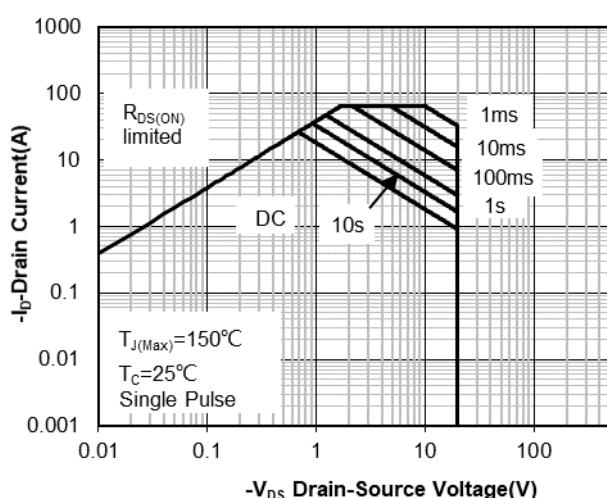


Figure 7. Safe Operation Area

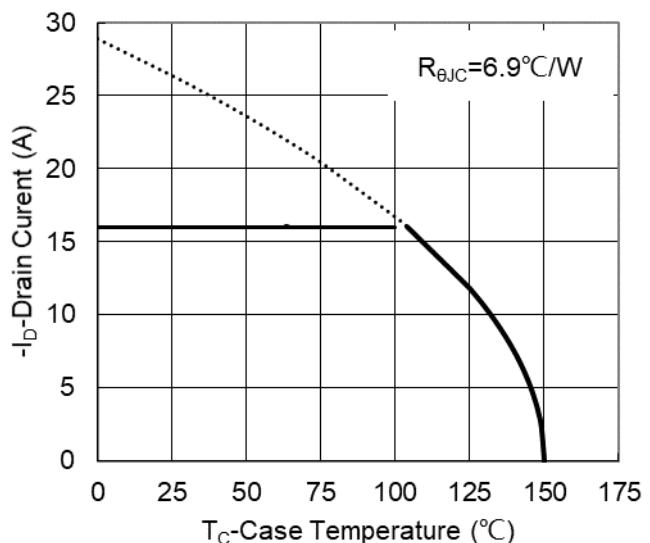
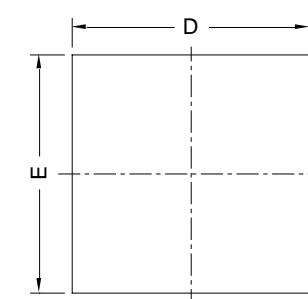
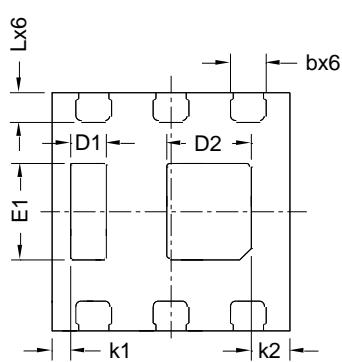


Figure 8. Maximum Continuous Drain Current vs Case Temperature

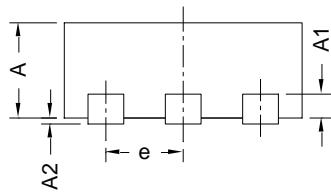
■ DFN2020-6L-E-0.8MM Package information



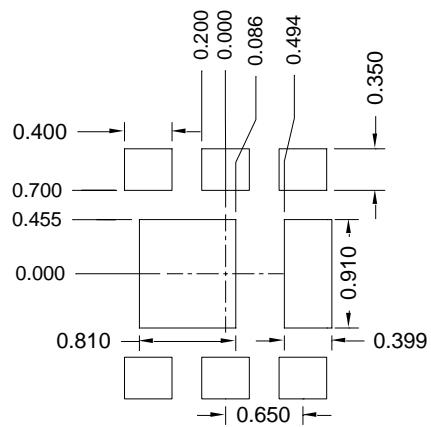
Top View
正面视图



Bottom View
背面视图



Side View
侧面视图



Suggested Solder Pad Layout
Top View

SYMBOL	MILLIMETER		
	MIN	NOM	MAX
D	1.90	2.00	2.10
E	1.90	2.00	2.10
A	0.70	0.80	0.90
A1	0.20 BSC		
A2	0.10		
D1	0.20	0.30	0.40
D2	0.61	0.71	0.81
E1	0.71	0.81	0.91
L	0.15	0.25	0.35
b	0.20	0.30	0.40
e	0.65 BSC		
k1	0.156 BSC		
k2	0.326 BSC		

Note:

1. Controlling dimension: in millimeters.
2. General tolerance: $\pm 0.10\text{mm}$.
3. The pad layout is for reference purposes only.

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